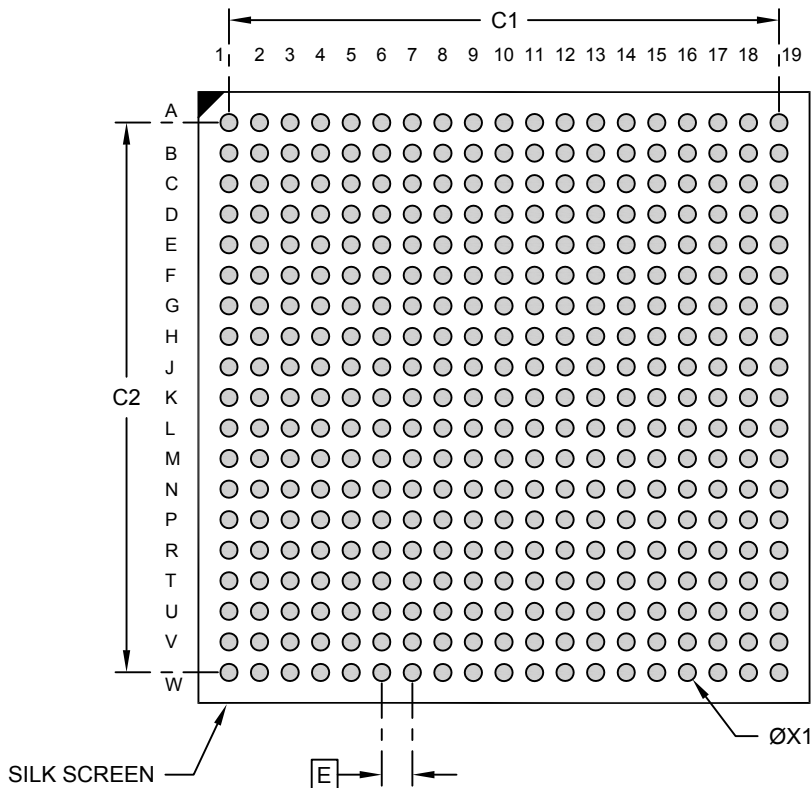


361-Ball Thin Fine Pitch Ball Grid Array (DYB) - 16x16 mm Body [TFBGA] Atmel Legacy Global Package Code CEP

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
		Dimension Limits	MIN	NOM	MAX
Contact Pitch	E		0.80 BSC		
Contact Pad Spacing	C1			14.40	
Contact Pad Spacing	C2			14.40	
Contact Pad Width (X20)	X1				0.45

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.